Packing • 1 x MX1-10FEP-D

• 1 x CPU Cooler (po

1 x Screw Pack (For HDD)

MX1-10FEP-D

Embedded System for GPU Computing Supports Intel[®] Coffee Lake Xeon / Core-i Powerful Processor

Introduction

64

MiTAC's MX1-10FEP-D embedded system is the next generation embedded system with Intel® Coffee Lake C246 workstation chipset which can support Xeon and Core-i LGA1151 socket type processor. The excellent performance, powerful processor, OCP/OVP power protection, and expandable design provide the solution for every complicated task and most types of application.

The MX1-10FEP-D's 8.5 liter chassis design and Xpandable module design give it the possibility to implement the complicated tasks and for every workspace and environment. Flexibilities also mean a rich array of I/O ports (including 2 x Ethernet RJ45, 8 x USB, 1 x HDMI, 1 x DVI-I, 1 x DisplayPort, 2 x COM, PCIe X16 + X1 slots, 3-pin Terminal Block Power Input, and 3 x Expansion doors) to add a variety of peripherals. Storage expandability is supported for 3 x high-density hard drives in 2.5" HDD bracket design. The reserved space for dual PCIe slots can be used for 1 x GFX Card installation. Two mPCle (shared with mSATA) slots provide the support of SSD and wireless interfaces which allow effortless connection to Wi-Fi and Bluetooth networks, and 4Gconnectivity. DIO/COM/LAN/PoE/Power Ignitoin expansion modules extend the capability and possibility to be used in more applications.



Dimension (mm)









Optional Peripheral



MX1-10FEP-D Embedded System for GPU Computing

SYSTEM					
CPU		9th & 8th Gen In 9th & 8th Gen In 65W, Core i9 8-c	ntel® Coffee Lake Xeon LGA1151 Socket Processor, 6- ntel® Coffee Lake LGA1151 Socket Processor, Core i7/ core TDP Max 35W	core TDP Max. 80W i5/i3 6-core TDP Max.	
Chipset		Intel [®] C246			
System Memory			2 x 260-pin SO-DIMM, Max. 32GB (Xeon: ECC; Core-i:	Non-ECC)	
Graphics		Intel® HD Graphi		/	
Display Interface		HDMI, DisplayPo	ort, DVI-I		
Storage Slot			(1 w/ Removable HDD Bay, 2 w/ Internal HDD Brack	(et)	
Ethernet			ga LAN + I210-IT Giga LAN		
Audio		Realtek® ALC662			
I/O Chipset		Nuvoton NCT61			
TPM		Nuvoton NPCT7	50AAAYX		
Expansion Slot		0	42 / 2260 / 2280 M key (PCIe X4 / SATA) eless: 2 x Mini PCIe Full / Half size (USB / PCIe / SATA), ·	w/ SIM Card Holder	
			Wireless: M.2 2230 E key (PCIe / USB)		
			Cle 3.0 X1 (Option: 2 x PCle 3.0 X8)		
Indicator		Power LED, HDD	Power LED, HDD LED, DIO LED, LAN1 & 2 ACT / SPEED		
		2 x USB 3.0			
FRONT I/O		1 x HDMI 1.4			
			2 x SIM Card Slot w/ Cover		
		1 x 2.5" SATAIII HDD / SSD Bay			
		4 x USB 3.1 Gen 2 (Gbps), 2 x USB 2.0, 2 x RJ-45 , 1 x DisplayPort 1.2, 1 x DVI-I, 1 x PS/2			
			2 x RS232 / 422 / 485 (Support Power 5V / 12V), 1 x Mic-in, 1 x Line-out		
		1 x 2-pin Terminal Block Remote Power on / off			
REAR I/O		1 x 2-pin Terminal Block Remote Power reset			
			1 x 4-pin Terminal Block External Fan Connector		
			1 x 3-pin Terminal Block Power Input		
		4 X SMA Antenno	a (Optional for WiFi/LTE function)		
POWER REQUIREMENT		0, 40V/14/1-1- D			
	_	7~40V WIDE ROS	ge DC Input w/ Terminal Block Connectivity		
MECHANICAL		a Fault ()			
Thermal Design			a. Fanless w/o Venting Holes		
1			b. With 2 x Internal System Fan (Supporting NVIDIA P4/T4/GTX1650/GTX1660 GPU Cards)		
		Malling a such / T	Wallmount / Top cover: Aluminum Alloy, Bezel and chassis: Steel		
Mounting / Material			,		
Dimension			o cover: Aluminum Alloy , Bezel and chassis: Steel ''' (268 mm x 246 mm x 128 mm)		
		10.6" x 9.7" x 5.0	" (268 mm x 246 mm x 128 mm)	_	
Dimension ENVIRONMENTAL	-	10.6" x 9.7" x 5.0 35W TDP Processo	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C	-	
Dimension	-	10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Proce	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C	-	
Dimension ENVIRONMENTAL	-	10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Proce 71~80W TDP Proce	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C	ntion	
Dimension ENVIRONMENTAL	_	10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Proce 71~80W TDP Proce *The operating te	"' (268 mm x 246 mm x 128 mm) or: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installa	ation.	
Dimension ENVIRONMENTAL Operating Temperature		10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Proce 71~80W TDP Proce *The operating te **with 0.7m/s Air F	"' (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installe flow and Wide Temperature Memory/Storage	ation.	
Dimension ENVIRONMENTAL		10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Proce 71~80W TDP Proce *The operating te **with 0.7m/s Air F 10%~90% R/H (N	"' (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installe flow and Wide Temperature Memory/Storage Ion-condensing)	ation.	
Dimension ENVIRONMENTAL Operating Temperature		10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Proce 71~80W TDP Proce *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gri	"' (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installe ilow and Wide Temperature Memory/Storage Ion-condensing) ms, 5-500 Hz, 3 Axes	ation.	
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity		10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Processo 71~80W TDP Processo *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord Operating, 50 G (w/ SSD, accord	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed low and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ding to IEC60068-2-64) Grms, Half-sine 11 ms Duration ding to IEC60068-2-27)	ation.	
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity Vibration Resistance Shock Resistance		10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Processo 71~80W TDP Processo *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord Operating, 50 G (w/ SSD, accord EMC: CE & FCC	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed low and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ting to IEC60068-2-64) Grms, Half-sine 11 ms Duration ting to IEC60068-2-27)	ation.	
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity Vibration Resistance		10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Proces 71~80W TDP Proce *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord Operating, 50 G (w/ SSD, accord EMC: CE & FCC Safety: complia	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed low and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ding to IEC60068-2-64) Grms, Half-sine 11 ms Duration ding to IEC60068-2-27) nt with LVD,EN60950-1 / EN62368-1	ation.	
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity Vibration Resistance Shock Resistance Certification		10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Proces 71~80W TDP Proce *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord Operating, 50 G (w/ SSD, accord EMC: CE & FCC Safety: complia	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed low and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ting to IEC60068-2-64) Grms, Half-sine 11 ms Duration ting to IEC60068-2-27)	ation.	
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity Vibration Resistance Shock Resistance Certification OS		10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Processo 71~80W TDP Proce *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord EMC: CE & FCC Safety: complia Compliant with	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed flow and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ding to IEC60068-2-64) Grms, Half-sine 11 ms Duration ding to IEC60068-2-27) nt with LVD,EN60950-1 / EN62368-1 EN50155/EN50121/E-mark	ation.	
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity Vibration Resistance Shock Resistance Certification OS OS Support		10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Processo 71~80W TDP Processo *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord Operating, 50 G (w/ SSD, accord Coperating, 50 G (w/ SSD, accord EMC: CE & FCC Safety: compliant Compliant with Windows* 10 64-	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed low and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ding to IEC60068-2-64) Grms, Half-sine 11 ms Duration ding to IEC60068-2-27) nt with LVD,EN60950-1 / EN62368-1	ation.	
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity Vibration Resistance Shock Resistance Certification OS	forma	10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Processo 71~80W TDP Processo *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord Operating, 50 G (w/ SSD, accord Coperating, 50 G (w/ SSD, accord EMC: CE & FCC Safety: compliant Compliant with Windows* 10 64-	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed flow and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ding to IEC60068-2-64) Grms, Half-sine 11 ms Duration ding to IEC60068-2-27) nt with LVD,EN60950-1 / EN62368-1 EN50155/EN50121/E-mark	ation.	
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity Vibration Resistance Shock Resistance Certification OS OS Support	format PCle Slot	10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Processo 71~80W TDP Processo *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord Operating, 50 G (w/ SSD, accord Coperating, 50 G (w/ SSD, accord EMC: CE & FCC Safety: compliant Compliant with Windows* 10 64-	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed flow and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ding to IEC60068-2-64) Grms, Half-sine 11 ms Duration ding to IEC60068-2-27) nt with LVD,EN60950-1 / EN62368-1 EN50155/EN50121/E-mark	ation.	
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity Vibration Resistance Shock Resistance Certification OS OS Support Ordering In		10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Processo 71~80W TDP Processo *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord Operating, 50 G (w/ SSD, accord Coperating, 50 G (w/ SSD, accord EMC: CE & FCC Safety: compliant Compliant with Windows* 10 64-	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed ilow and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ding to IEC60068-2-64) Grms, Half-sine 11 ms Duration ding to IEC60068-2-27) nt with LVD,EN60950-1 / EN62368-1 EN50155/EN50121/E-mark -bit, Linux (support by request)		
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity Vibration Resistance Shock Resistance Certification OS OS Support Ordering In Model Number	PCIe Slot	10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Processo 71~80W TDP Processo *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord Operating, 50 G (w/ SSD, accord Coperating, 50 G (w/ SSD, accord EMC: CE & FCC Safety: complia Compliant with Windows* 10 64-	" (268 mm x 246 mm x 128 mm) m: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed flow and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ting to IEC60068-2-64) Erms, Half-sine 11 ms Duration ting to IEC60068-2-27) nt with LVD,EN60950-1 / EN62368-1 EN50155/EN50121/E-mark -bit, Linux (support by request) Power	AC Adaptor	
Dimension ENVIRONMENTAL Operating Temperature Operating Humidity Vibration Resistance Shock Resistance Certification OS OS Support Ordering In Model Number MX1-10FEP-D-C246-FL	PCIe Slot X16 + X1	10.6" x 9.7" x 5.0 35W TDP Processo 51~65W TDP Proces 71~80W TDP Proce *The operating te **with 0.7m/s Air F 10%~90% R/H (N Operating, 5 Gr (w/ SSD, accord Operating, 50 G (w/ SSD, accord Coperating, 50 G (w/ SSD, accord EMC: CE & FCC Safety: complia Compliant with Windows* 10 64- tion Thermal Fanless	" (268 mm x 246 mm x 128 mm) pr: -40°C to 70°C essor: -40°C to 50°C essor: -40°C to 40°C mperature is based on fanless design w/o GPU card installed flow and Wide Temperature Memory/Storage lon-condensing) ms, 5-500 Hz, 3 Axes ding to IEC60068-2-64) frms, Half-sine 11 ms Duration ding to IEC60068-2-27) nt with LVD,EN60950-1 / EN62368-1 EN50155/EN50121/E-mark -bit, Linux (support by request) Power 9~48V Wide Rage DC Input w/ Terminal Block Connectivity	AC Adaptor None	



1 x 3-pin Terminal Block Conn

• 1 x DVI to VGA converter

2 x 2-pin Terminal Block Conr

ector	 1 x 4-pin Terminal Block Connector
	 1 x Wall Mount Bracket
nector	• 1 x Driver CD